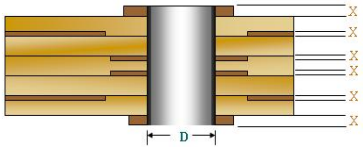
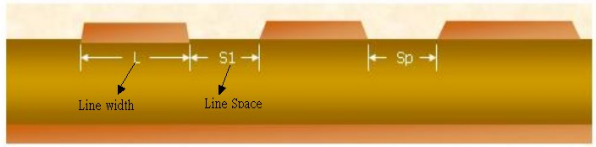
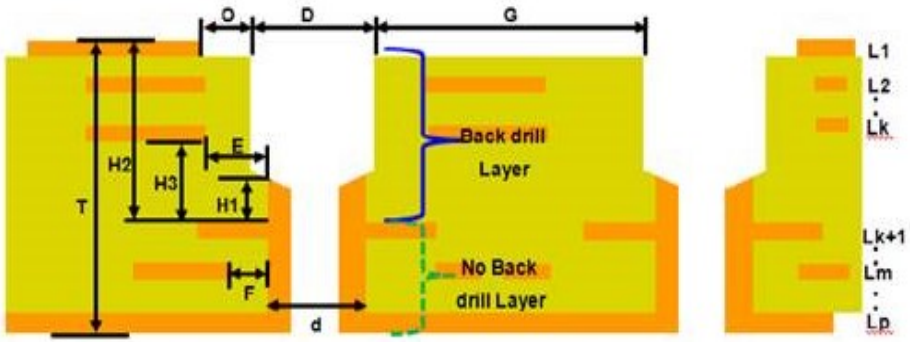
Technology Capability

	DESCRIPTION	2020	2021
材料與結構 Material & Construction	●成品板厚(Finished board thickness)	●6~200mil(0.15~5.0mm)	●6~200mil(0.15~5.0mm)
	●Tg	●130~240˚C	●130~240˚C
	●最小基板厚度(Min. core thickness)	●0.002" H/H(0.051mm)	●0.002" H/H(0.051mm)
	●層數 Layer count	●2~26 Layers	●2~28 Layers
壓合 Laminating	●板厚公差(壓合後) board thickness tolerance (after lamination)	●±3mil or ±10% (0.076mm)	●±3mil or ±10% (0.076mm)
	●層與層的對準度 Layer to Layer registration	●±3mil (0.076mm)	●±3mil (0.076mm)
鑽孔 Drilling	●最小鑽孔孔徑 (Min.) drill bit 	●6.0mil (0.15mm)	●6.0mil (0.15mm)

Technology Capability

	DESCRIPTION	2020	2021
導線 Conductor	●內層最小線寬/線距 I/L(Min.)width/space(Hoz for I/L) ●外層最小線寬/線距 O/L(Min.)width/space(1/3 oz for O/L) ●內層最大銅厚 I/L(Max.)copper weight • *Line Width and Spacing* 	●2.3/2.3 mil (0.058mm/0.058mm) ●2.7/2.75 mil (0.069mm/0.070mm) ●6oz ●6oz	●2.3/2.3 mil (0.058mm/0.058mm) ●2.7/2.75 mil (0.069mm/0.070mm) ●6oz ●6oz
電鍍銅 Copper Plating	●縱橫比-->T/F (Max.) aspect ratio	●Finish -->1:13	Finish -->1:15

Technology Capability

	DESCRIPTION	2020	2021
定深鑽 BackDrill	●導通孔(d) drill bit	●≧6.0mil (0.15mm)	●≧6.0mil (0.15mm)
	●背鑽孔(D) back drill	●d+10mil(d+0.25mm)	●d+10mil(d+0.25mm)
	●PCB板厚(T) PCB board thickness	●T≦200mil (5.08mm)	●T≦200mil (5.08mm)
	●背鑽殘厚(H1) back drill depth	●≧4mil (0.1mm)	●≧4mil (0.1mm)
	●深度控制公差 Depth tolerance	●±4mil (0.1mm)	●±4mil (0.1mm)
	●定深最小孔徑(Min.) drill bit	●15.7mil (0.4mm)	●13.8mil (0.35mm)